

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1	1	-	TB6634FNG	TOSHIBA	-	SSOP30	10.2 x 7.6
2	IC2	1	-	TPD4206F	TOSHIBA	-	SSOP30	20.0 x 14.2
3	R1,R2,R12, R13,R14,R15	6	300 Ω	-	-	100 mW ± 5%	-	1.6 x 0.8 (0603)
4	R3, R6	2	10 kΩ	-	-	100 mW ± 0.5%	-	1.6 x 0.8 (0603)
5	R4, R5	2	100 kΩ	-	-	100 mW ± 0.5%	-	1.6 x 0.8 (0603)
6	R7	1	5.1 kΩ	-	-	100 mW ± 1%	-	1.6 x 0.8 (0603)
7	R8	1	10 kΩ	-	-	100 mW ± 1%	-	1.6 x 0.8 (0603)
8	R9	1	140 mΩ	SL1TTER	KOA	1 W, ±1%	-	6.3 x 3.1 (2512)
9	R10	1	2 MΩ	-	-	1 W ± 5%	-	6.3 x 3.1 (2512)
10	R11	1	17.4 kΩ	-	-	250 mW ± 1%	-	2.0 x 1.2 (0805)
11	C1	1	10 μF	-	-	Chemical, 25 V, ±10%	-	2.0 x 1.2 (0805)
12	C2	1	0.1 μF	-	-	Ceramic, 25 V, ±10%	-	2.0 x 1.2 (0805)
12	C3, C7, C12	3	2.2 μF	-	-	Ceramic, 25 V, ±10%	-	2.0 x 1.2 (0805)
13	C4	1	330 pF	-	-	Ceramic, 25 V, ±5%	-	1.6 x 0.8 (0603)
14	C5	1	10 μF	-	-	Ceramic, 25 V, ±20%	-	2.0 x 1.2 (0805)
15	C6, C9, C10, C11	4	100 nF	-	-	Ceramic, 25 V, ±10%	-	1.6 x 0.8 (0603)
16	C8, C13	2	1 μF	ECQE6105KF	Panasonic	Polypropylene Film, 650 V, ±10 %	DIP	-
17	C14	1	1 μF	-	-	Chemical, 25 V, ±10%	-	2.0 x 1.2 (0805)
18	C15	1	1000 pF	-	-	Ceramic, 25 V, ±10%	-	2.0 x 1.2 (0805)
19	S1, S2, S3	3	-	HW-101A	ASK	Hall Sensor	4SOP	-

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